

E1 2. (Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body comprises a plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, and predetermined ones of the internal surfaces define the conduction sections as the substrate main body is cut along corresponding ones of the through-holes.

3. (Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections are formed on a surface opposite of a mounting surface of the semiconductor device and are electrically connected to the leads through the through-holes.

4. (Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body has a plurality of through-holes for each of the leads, and the conduction sections are formed on a surface opposite of the mounting surface of the device and are electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

E2 6. (Amended) An electronic apparatus having a circuit substrate mounted with the substrate for semiconductor apparatus according to claim 1.

REMARKS

Claims 1-4, 6-12 and 19-25 are pending. By this Amendment, claims 1-4 and 6 are amended. Reconsideration of the Application in view of the above amendment and the following remarks is respectfully requested.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).